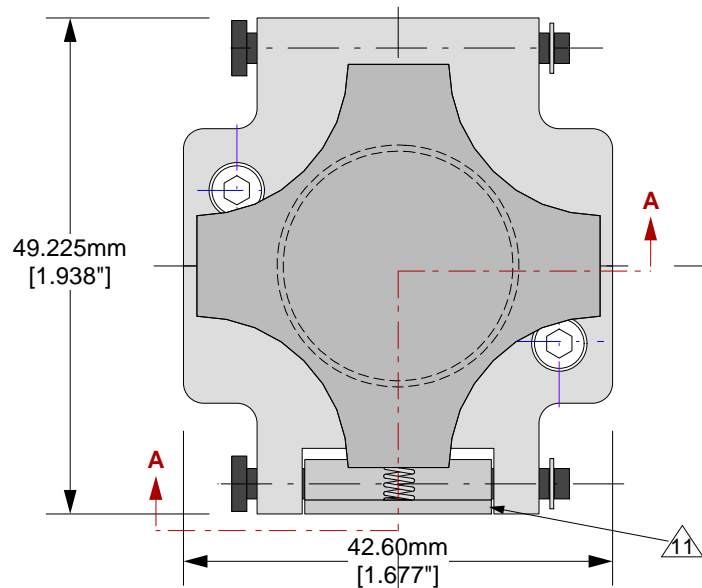
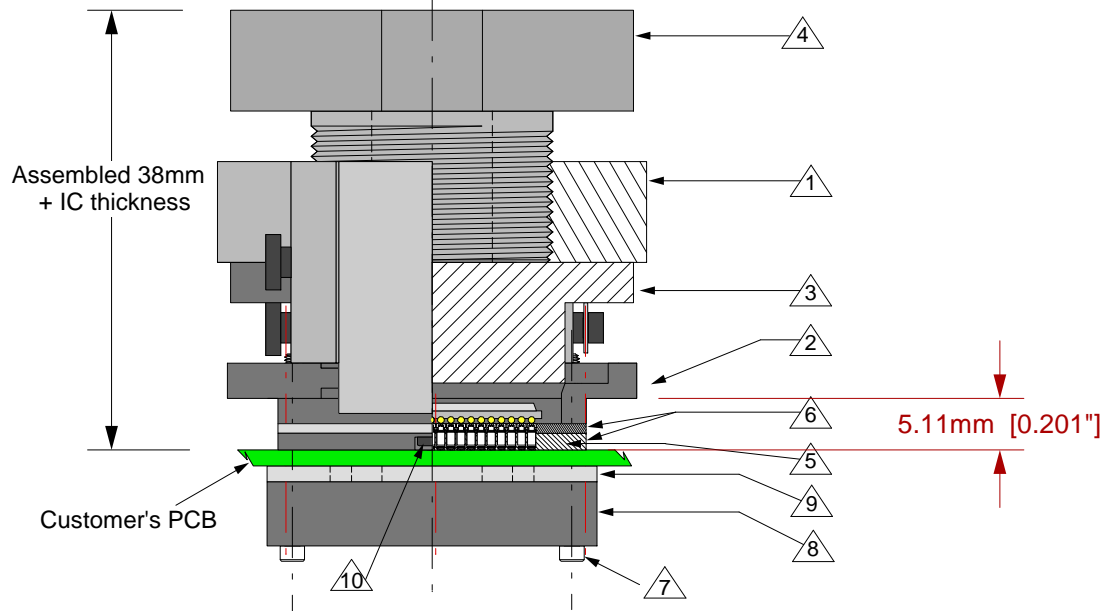


Top View



Side View  
(Section AA)



**Features**

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

**Materials:**

- 1 Clam Shell Lid: Black anodized 7075 Aluminum. Height = 20 mm.
- 2 Socket Base: Black anodized 7075 Aluminum. Height = 6 mm.
- 3 Compression Plate: Black anodized 7075 Aluminum. Thickness = 12 mm.
- 4 Compression Screw: Clear anodized 7075 Aluminum. Height = 27 mm, Fluted Knob
- 5 Pogo Pin:  
Plungers - Hardened Steel/ Gold plated  
Barrel - Copper Alloy/ Gold plated  
Spring - Stainless Steel/ Gold wire
- 6 Pogo Pin Guides: Ultem 1000.
- 7 Socket Base Screw: Socket Head Cap Screw, 18-8 SS, 0-80 Thread, 3/4" long.
- 8 Backing Plate: Black anodized 7075 Aluminum
- 9 Insulation Plate: FR4/G10
- 10 Pogo Pin Guide Screw: Pan head phillips, 18-8 SS, 0-80 thread, 3/16" long.
- 11 Latch: Black anodized 7075 Aluminum.

**SS-BGA400-01 Drawing**

Status: Released

Scale: 1.25:1

Rev: A



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Tele: (952) 229-8200  
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Drawing: E Smolentseva

Date: 4/21/10

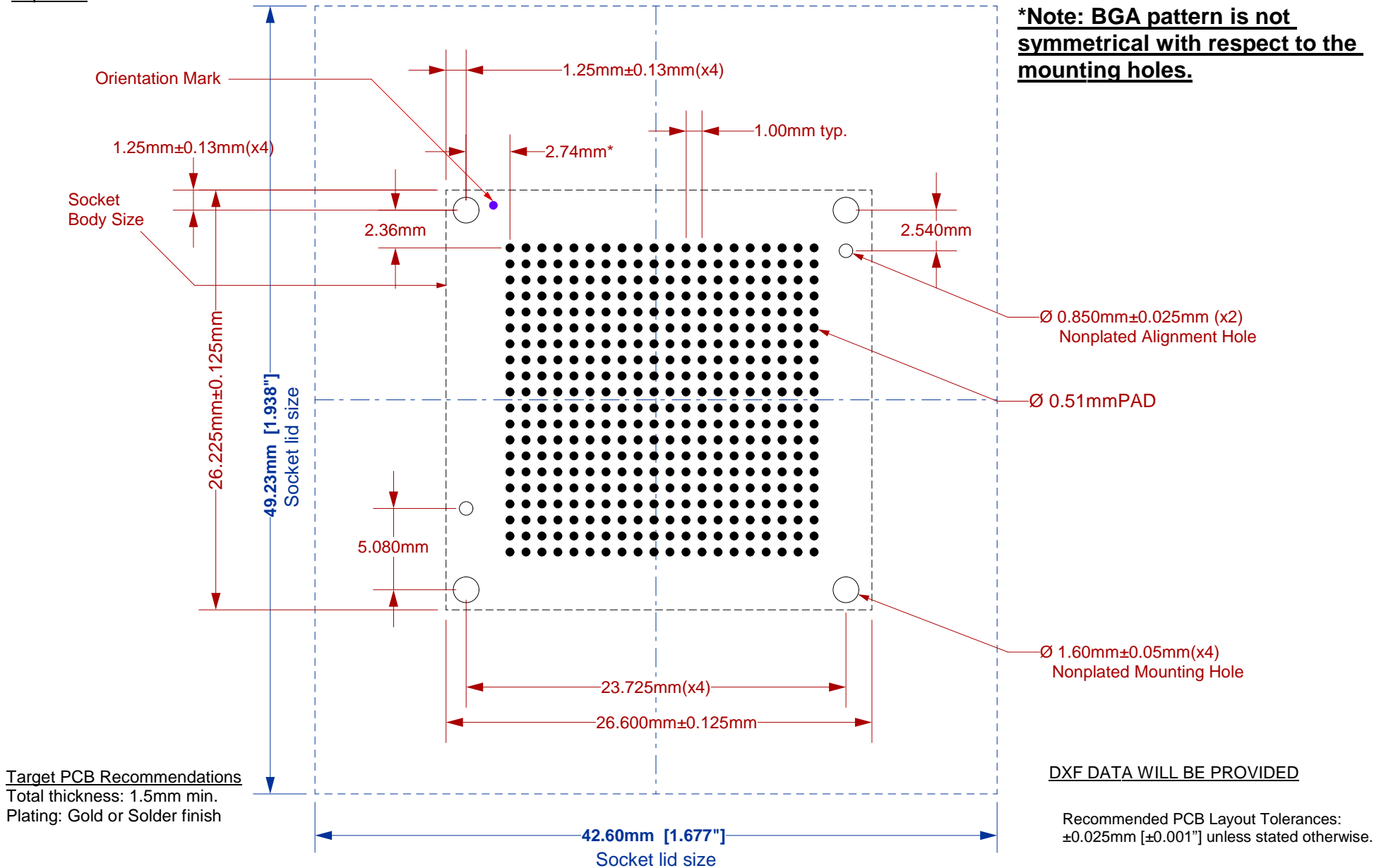
File: SS-BGA400A-01 Dwg

Modified:

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout  
Top View


**\*Note: BGA pattern is not symmetrical with respect to the mounting holes.**

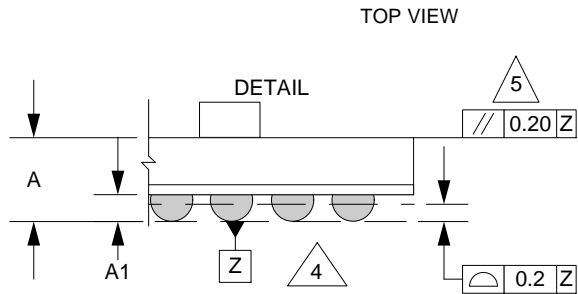
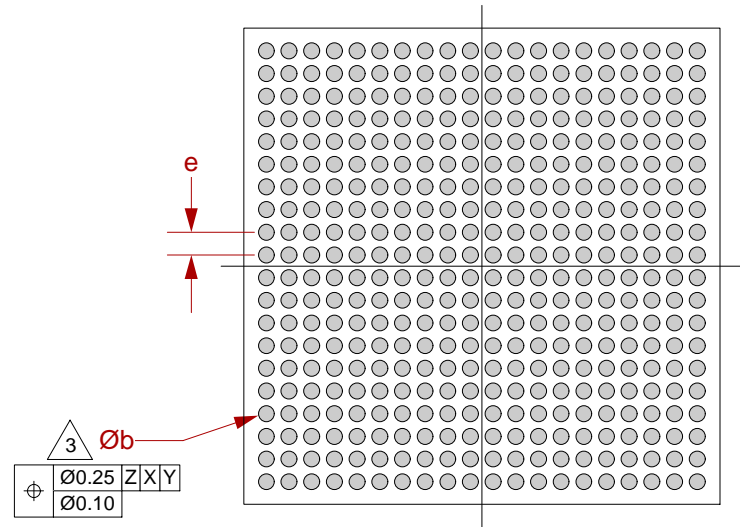
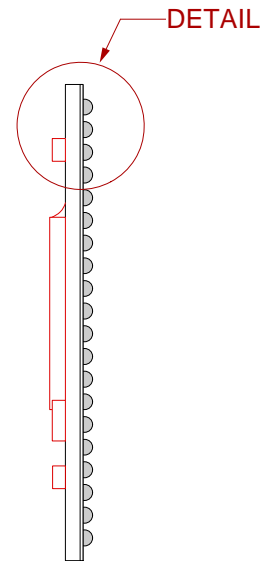
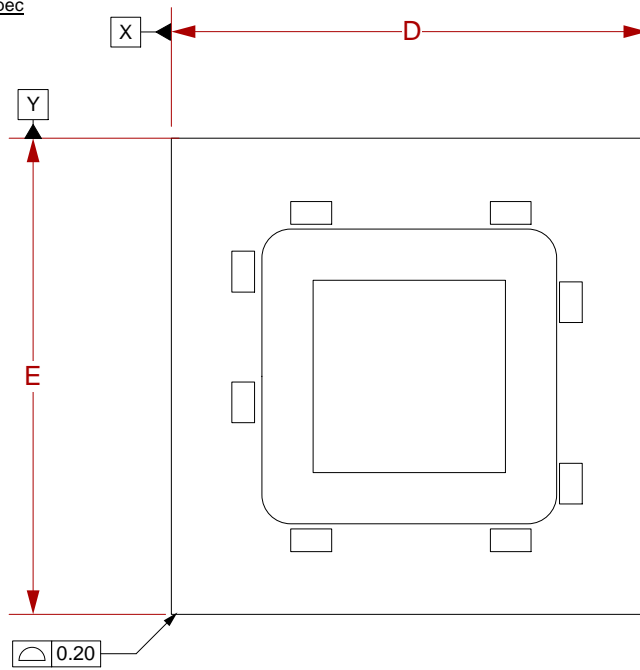


Target PCB Recommendations  
Total thickness: 1.5mm min.  
Plating: Gold or Solder finish

DXF DATA WILL BE PROVIDED

Recommended PCB Layout Tolerances:  
 $\pm 0.025\text{mm}$  [ $\pm 0.001$ "] unless stated otherwise.

	<b>SS-BGA400-01 Drawing</b>		Status: Released	Scale: 1.25:1	Rev: A
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			File: SS-BGA400A-01 Dwg		Modified:



SIDE VIEW

BOTTOM VIEW

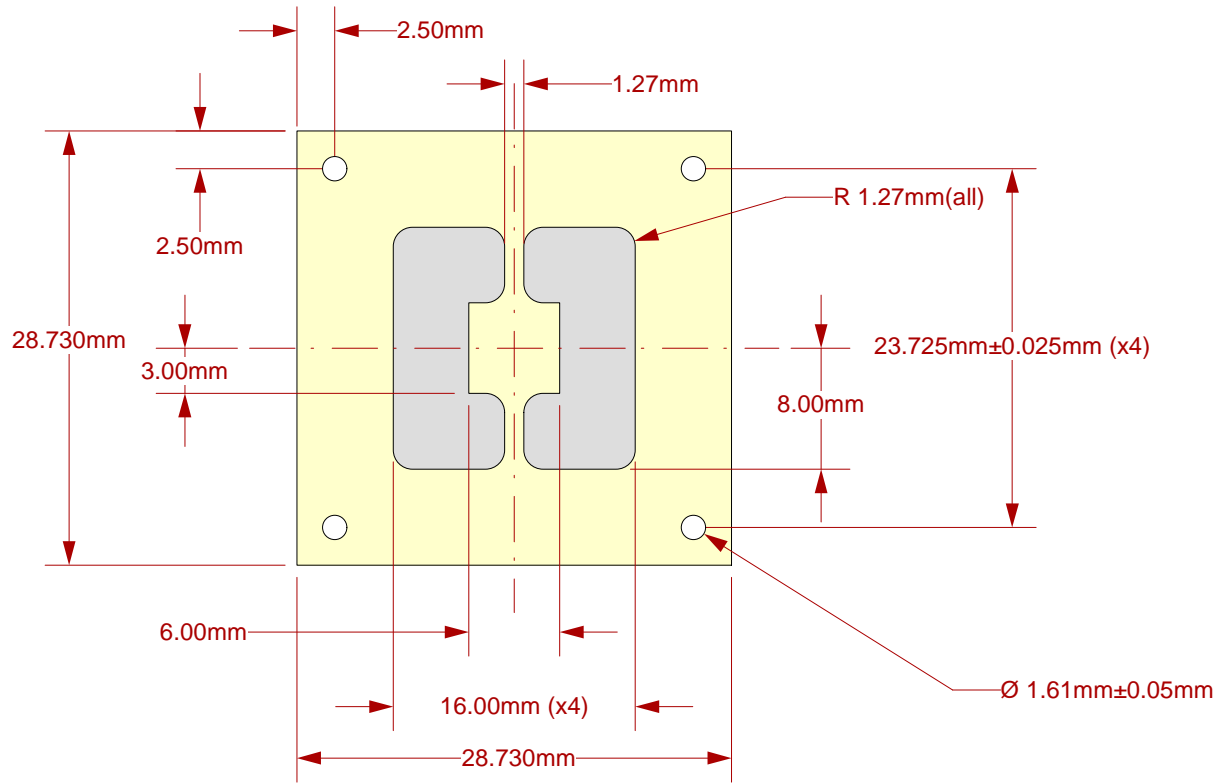
1. Dimensions are in millimeters.
  2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
  - 4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
  - 5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.55
A1	0.17	0.37
b		0.55
D	21.00 BSC	
E	21.00 BSC	
e	1.0 BSC	

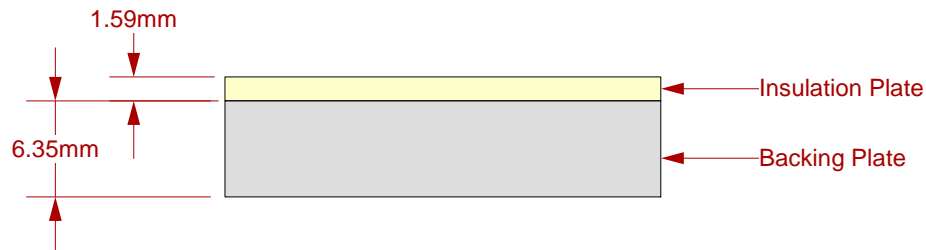
20x20 Array

	<b>SS-BGA400-01 Drawing</b>	Status: Released	Scale: 1.25:1	Rev: A
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		File: SS-BGA400A-01 Dwg	Modified:	

Top View




Side View

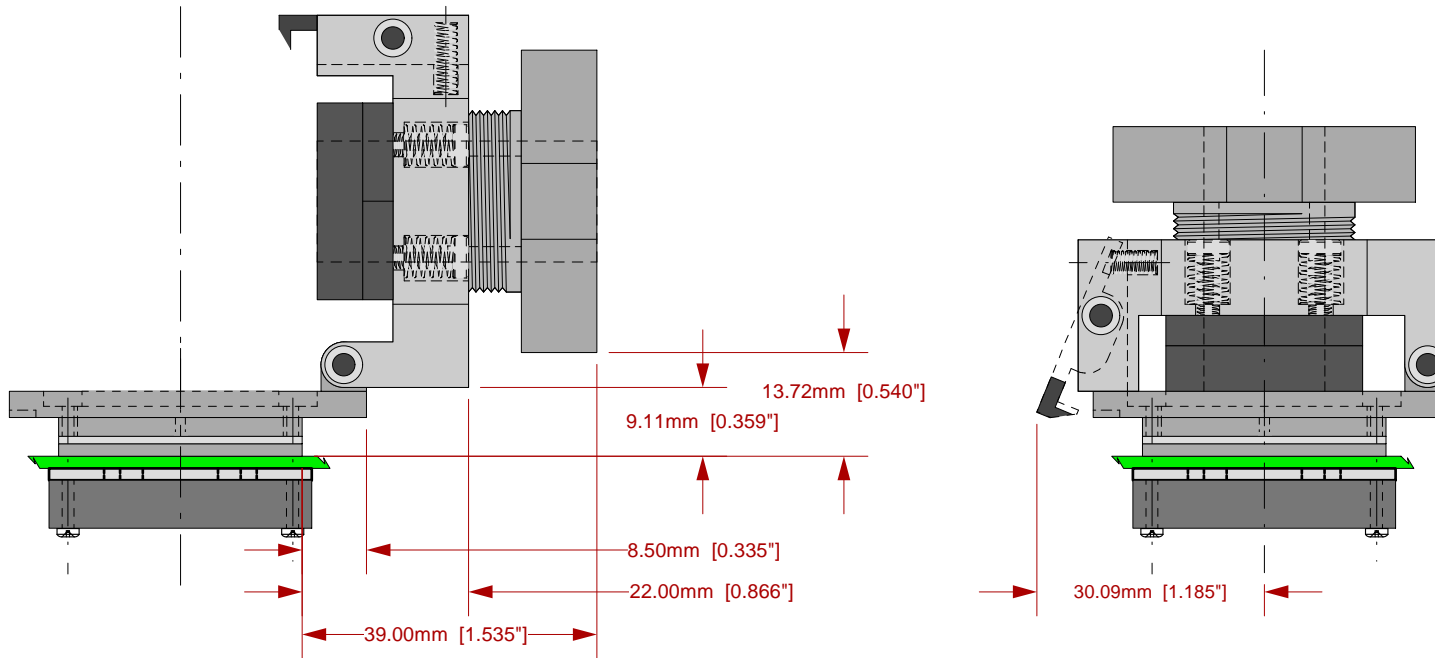
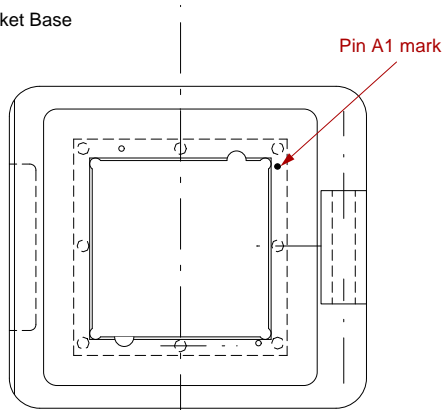


Description: Backing Plate with Insulation Plate


All dimensions are in mm.  
All tolerances are +/- 0.125mm.  
(Unless stated otherwise)

	<b>SS-BGA400-01 Drawing</b> © 2010 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Status: Released	Scale: 1.25:1	Rev: A
		Drawing: E Smolentseva		Date: 4/21/10
		File: SS-BGA400A-01 Dwg		Modified:

Top View of Socket Base



All Tolerances:  $\pm 0.125\text{mm}$  (unless stated otherwise). Materials and specifications are subject to change without notice.

	<b>SS-BGA400-01 Drawing</b>	Status: Released	Scale: 1.25:1	Rev: A
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		File: SS-BGA400A-01 Dwg	Modified:	